ABSTRACT

The object of the present invention is to provide a free and precise control of the plating amount while easily determining a selected portion to be plated.

Small balls 24 are arranged at, and adhered or bonded to, via holes 22 of a TAB tape 21 and the small balls 24 are then melted so that a copper wiring 23 exposed at the via holes 22 of the TAB tape 21 can be selectively plated with a different metal to enable selected portions of a substrate for electronic devices to be partially plated easily and precisely.